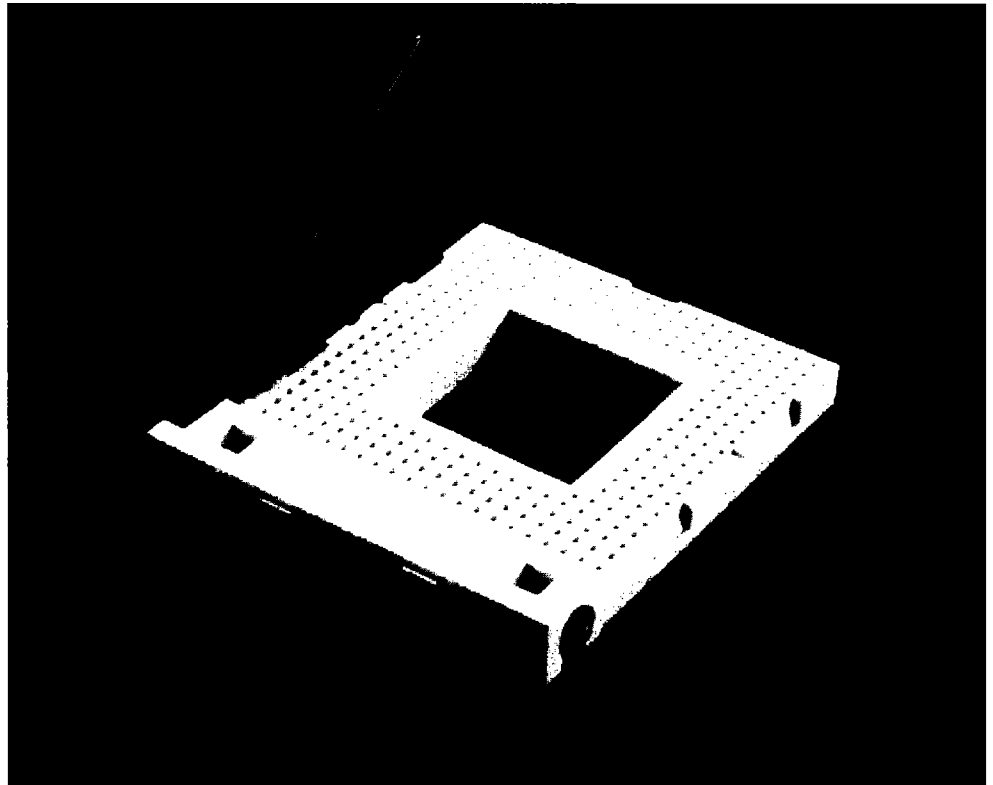


## PGA Sockets — Single Lever (SL) ZIF

### Product Facts

- Zero insertion force actuation to facilitate device socketing
- Convenient single lever (SL) handle operation requires no tools
- Contacts are plated with 30 microinches of gold
- Large funnel entry cavity
- Normally closed, full wiping contacts
- Lower in cost than most other ZIF-style PGA sockets
- Positive detent-locking lever eliminates inadvertent opening
- Housing design permits the addition of a heat sink



AMP Single Lever (SL) Zero Insertion Force (ZIF) PGA Sockets are designed specifically for the new Intel upgrade devices, including Intel's next generation Pentium™ processor.

SL ZIF sockets feature single-lever action that operates a free-moving cam, allowing the substrate to be inserted and extracted without force when in the open position. In the closed position, the normally closed contacts maintain a constant pressure on the substrate pins, providing excellent electrical integrity. The lever actuator has positive stops in both the open and closed positions, preventing accidental overstress and possible subsequent damage.

The sockets are designed to permit the attachment of a quick connect/disconnect heat sink to the socket housing for mechanical stability in high shock and vibration environments.

### Performance Characteristics

**Operating Temperature:**  
-55°C to +105°C

**Contact Resistance:**  
20 milliohms max., initial  
30 milliohms max., final

**Dielectric Withstanding Voltage:**  
1000 VAC

**Insulation Resistance:**  
5000 megohms min., initial

**Durability:**  
50 cycles

**Handle Actuation Force:**  
2 lbs. [8.9 N] Average

### Testing Information

**Physical Shock/Vibration:**  
Levels may vary with the size of the heat sink used and type of attachment method

**Thermal Shock:**  
25 cycles between -55°C and +105°C

**Temperature/Humidity Cycling:**  
10 cycles between 25°C and 65°C at 98% RH

**Temperature Life:**  
105°C for 300 hours

### Technical Document

**Design Objectives**  
108-1464

**Application Specification**  
114-1078



## PGA Sockets — Single Lever (SL) ZIF (Continued)

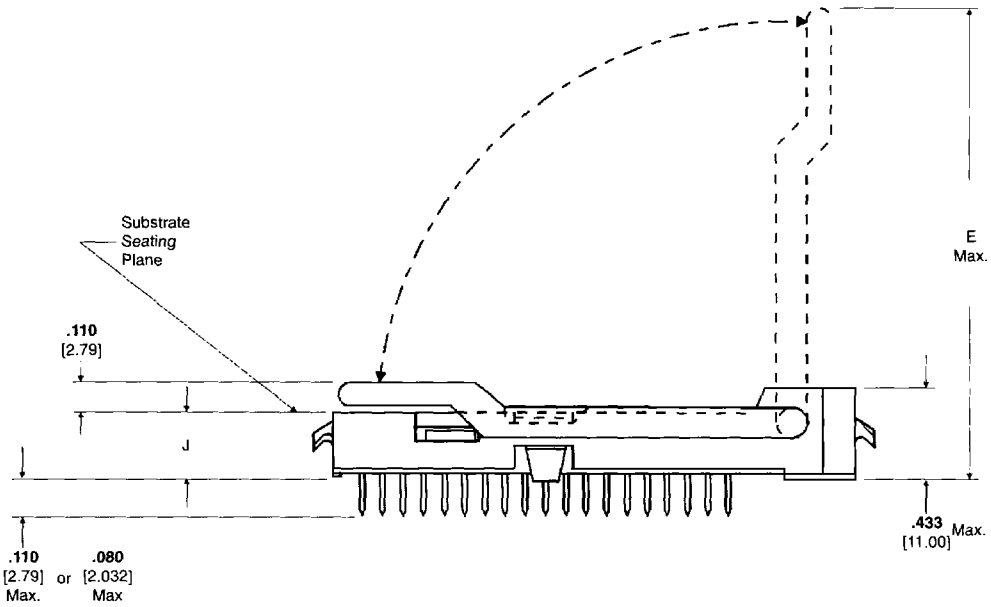
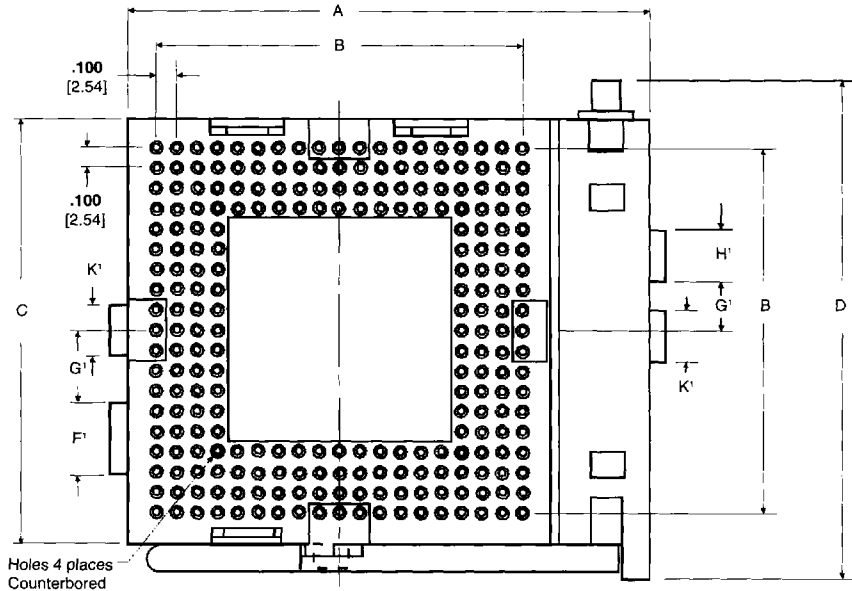
**.100 x .100 [2.54 x 2.54]  
Pattern**

**Material and Finish**

**Housing** — High temperature thermoplastic

**Contact** — Copper alloy with .000030 [0.00075] min. thick gold over .000050 [0.00127] min. thick nickel in contact area and .000150 [0.00381] min. thick tin-lead over .000050 [0.00127] min. thick nickel in soldertail area

**Actuator** — Zinc alloy



Grid Size	No. of Pos.	Dimensions										Grid Patterns, Solder Tail Length and Part Numbers, See pages:
		A	B	C	D	E	F'	G'	H'	J	K'	
17 x 17	168 and 169	2.224	1.600	1.858	2.050	2.244	.315	.315	.203	.318	—	122-123
		56.50	40.64	47.20	52.07	57.00	8.00	8.00	5.16	8.08		
19 x 19	235	2.421	1.800	2.055	2.255	2.441	.315	.315	.253	.318	.180	124-125
	237	61.50	45.72	52.20	57.28	62.00	8.00	8.00	6.43	8.08	4.57	
	238											
21 x 21	273	2.716	2.000	2.258	2.520	2.559	.315	.315	.303	.300	.180	126
		69.00	50.80	57.35	64.00	65.00	8.00	8.00	7.70	7.62	4.57	

<sup>1</sup> Dimensions pertain to sockets with heat sink feature only.

**Note:** Special SL ZIF Sockets with rotated patterns and left hand configurations are available. Contact AMP Incorporated for information.

## PGA Sockets — Single Lever (SL) ZIF (Continued)

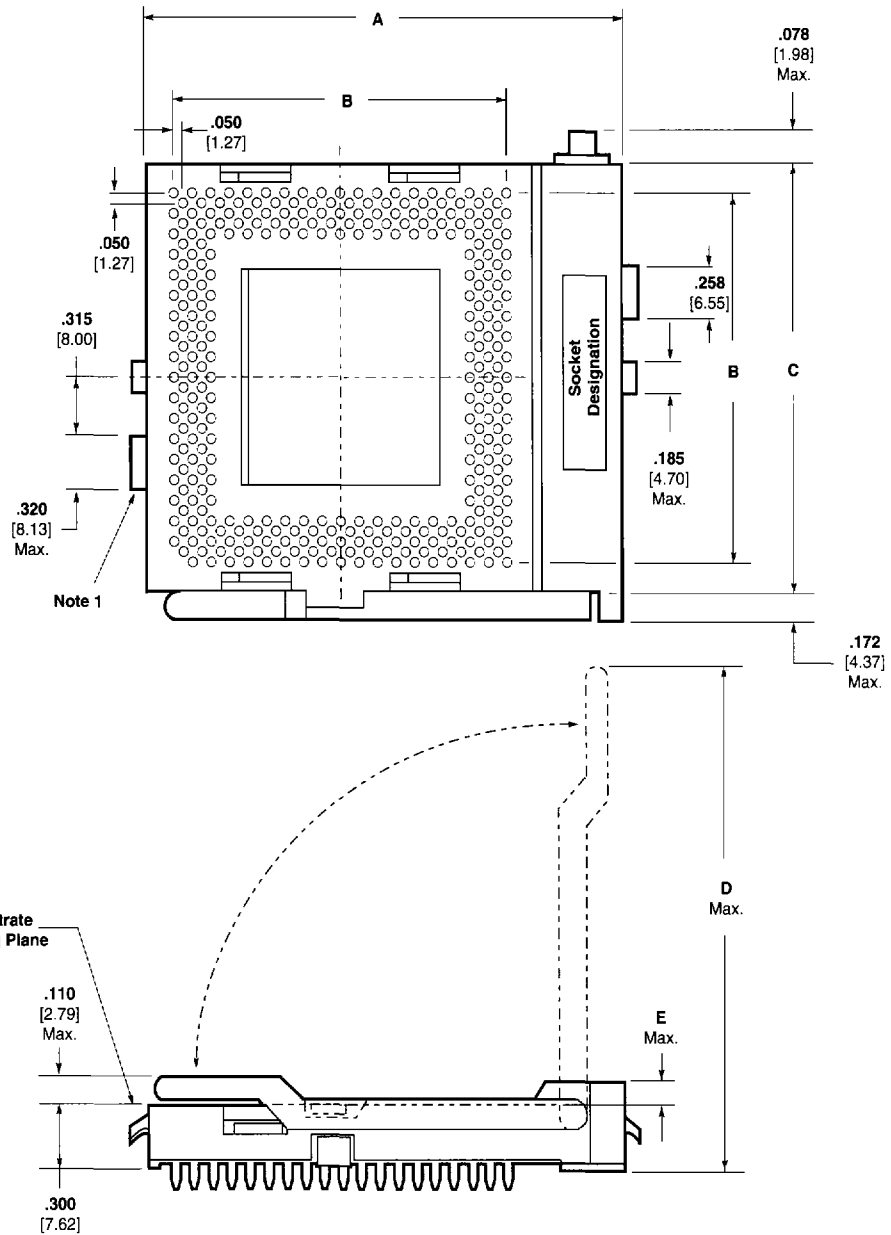
### Interstitial Pattern

### Material and Finish

**Housing** — High temperature thermoplastic

**Contact** — Copper alloy with .000030 [0.00075] min. thick gold over .000050 [0.00127] min. thick nickel in contact area and .000150 [0.00381] min. thick tin-lead over .000050 [0.00127] min. thick nickel in soldertail area

**Actuator** — Zinc alloy



**Note 1:**  
Quantity of bosses and location will vary with part number.

Grid Size	No. of Pos.	Dimensions					Grid Patterns, Solder Tail Length and Part Numbers, See Pages:
		A	B	C	D	E	
19 x 19	320	2.519	1.800	2.055	2.539	.129	125-126
		63.99	45.72	52.20	64.49	3.28	
22 x 22	499	2.764	2.100	2.535	2.756	.115	127
		70.21	53.34	64.39	70.00	2.92	